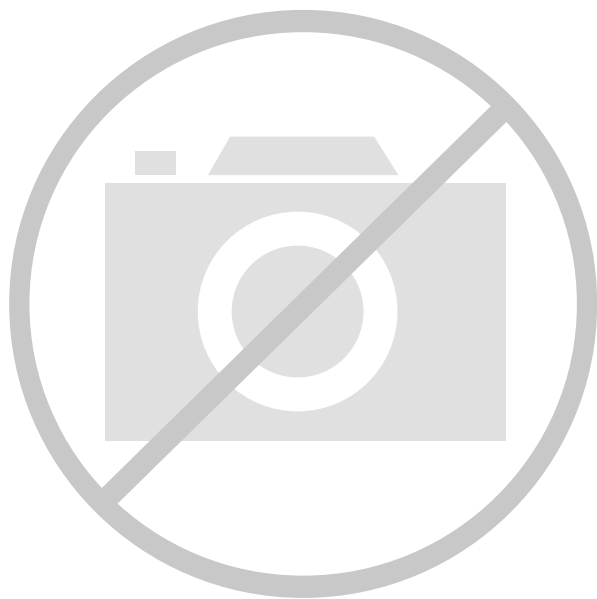




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	10000
Number of Logic Elements/Cells	40000
Total RAM Bits	4075520
Number of I/O	604
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga40ep1-5fcn1152i

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR 16x2 x 4 DPR 16x2 x 2	ROM 16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR 16x4 x 2 DPR 16x4 x 1	ROM 16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR 16x8 x 1	ROM 16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM 16x8 x 1

Routing

There are many resources provided in the LatticeSC devices to route signals individually or as busses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

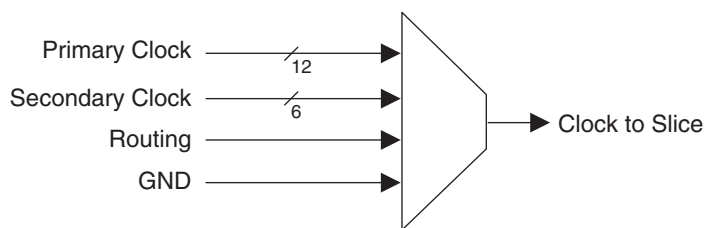
The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU) resources. The x1 and x2 connections provide fast and efficient connections in horizontal, vertical and diagonal directions. All connections are buffered to ensure high-speed operation even with long high-fanout connections.

The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

sysCLOCK Network

The LatticeSC devices have three distinct clock networks for use in distributing high-performance clocks within the device: primary clocks, secondary clocks and edge clocks. In addition to these dedicated clock networks, users are free to route clocks within the device using the general purpose routing. Figure 2-4 shows the clock resources available to each slice.

Figure 2-4. Slice Clock Selection

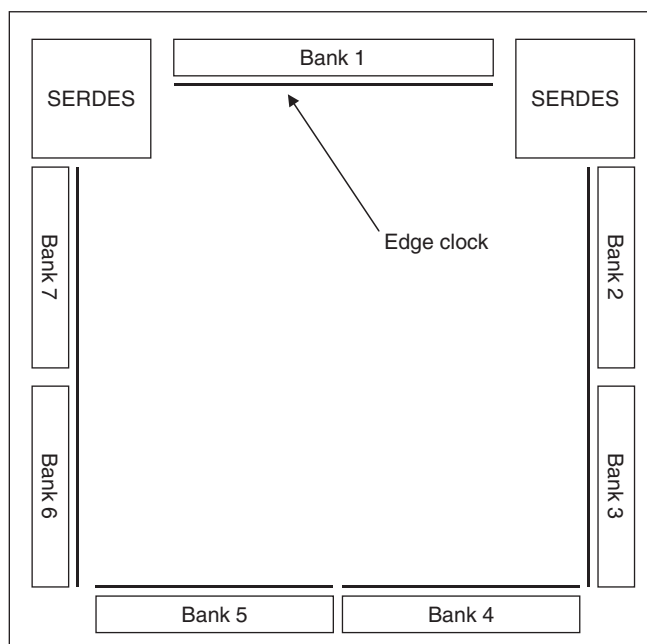


Note: GND is available to switch off the network.

Primary Clock Sources

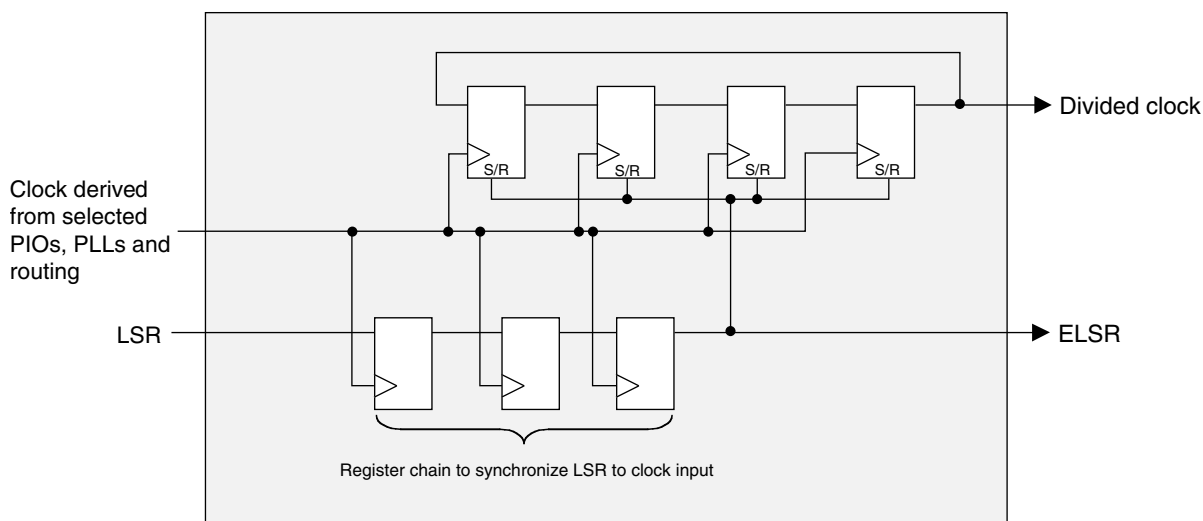
LatticeSC devices have a wide variety of primary clock sources available. Primary clocks sources consists of the following:

- Primary clock input pins
- Edge clock input pins
- Two outputs per DLL

Figure 2-7. Edge Clock Resources

Precision Clock Divider

Each set of edge clocks has four high-speed dividers associated with it. These are intended for generating a slower speed system clock from the high-speed edge clock. The block operates in a DIV2 or DIV4 mode and maintains a known phase relationship between the divided down clock and high-speed clock based on the release of its reset signal. The clock dividers can be fed from selected PIOs, PLLs and routing. The clock divider outputs serve as primary clock sources. This circuit also generates an edge local set/reset (ELSR) signal which is fed to the PIOs via the edge clock network and is used for the rest of the I/O gearing logic.

Figure 2-8. Clock Divider Circuit

Dynamic Clock Select (DCS)

The DCS is a global clock buffer with smart multiplexer functions. It takes two independent input clock sources and outputs a clock signal without any glitches or runt pulses. This is achieved irrespective of where the select signal is

toggled. There are eight DCS blocks per device, located in pairs at the center of each side. Figure 2-9 illustrates the DCS Block diagram.

Figure 2-9. DCS Block Diagram

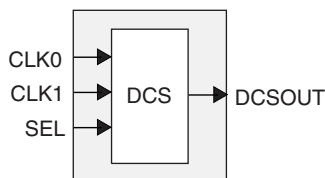
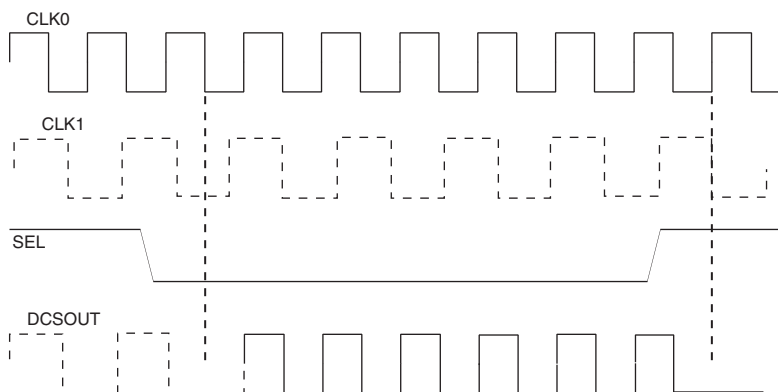


Figure 2-10 shows timing waveforms for one of the DCS operating modes. The DCS block can be programmed to other modes. For more information on the DCS, please see details of additional technical documentation at the end of this data sheet.

Figure 2-10. DCS Waveforms



Clock Boosting

There are programmable delays available in the clock signal paths in the PFU, PIC and EBR blocks. These allow setup and clock-to-output times to be traded to meet critical timing without slowing the system clock. If this feature is enabled then the design tool automatically uses these delays to improve timing performance.

Global Set/Reset

There is a global set/reset (GSR) network on the device that is distributed to all FFs, PLLs, DLLs and other blocks on the device. This GSR network can operate in two modes:

- asynchronous - no clock is required to get into or out of the reset state.
- synchronous - The global GSR net is synchronized to a user selected clock. In this mode it continues to be asynchronous to get into the reset state, but is synchronous to get out of the reset state. This allows all registers on the device to become operational in the same clock period. The synchronous GSR goes out of reset in two cycles from the clock edge where the setup time of the FF was met (not from the GSR being released).

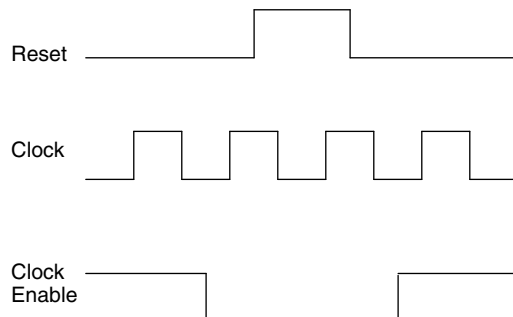
sysCLOCK Phase Locked Loops (PLLs)

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider and two clock output dividers. The input divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal.

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the low-to-high transition of the reset, as shown in Figure 2-16.

Figure 2-16. EBR Asynchronous Reset (Including GSR) Timing Diagram



If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becoming active.

These instructions apply to all EBR RAM, ROM, FIFO and shift register implementations. For the EBR FIFO mode, the GSR signal is always enabled and the WE and RE signals act like the clock enable signals in Figure 2-16. The reset timing rules apply to the RPRreset input vs. the RE input and the RST input vs. the WE and RE inputs. Both RST and RPRreset are always asynchronous EBR inputs. For the EBR shift register mode, the GSR signal is always enabled and the local RESET pin is always asynchronous.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled. For more information about on-chip memory, see TN1094, [On-Chip Memory Usage Guide for LatticeSC Devices](#).

Programmable I/O Cells (PIC)

Each PIC contains four PIOs connected to their respective PURESPEED I/O Buffer which are then connected to the PADs as shown in Figure 2-17. The PIO Block supplies the output data (DO) and the Tri-state control signal (TO) to PURESPEED I/O buffer, and receives input (DI) from the buffer. The PIO contains advanced capabilities to allow the support of speeds up to 2Gbps. These include dedicated shift and DDR logic and adaptive input logic. The dedicated resources simplify the design of robust interfaces.

Table 2-9. Supported Input Standards

Input Standard	V _{REF} (Nom.)	V _{CCIO} ¹ (Nom.)	On-chip Termination
Single Ended Interfaces			
LVTTL33 ³	—	3.3	None
LVC MOS 33, 25, 18, 15, 12 ³	—	3.3/2.5/1.8/1.5/1.2	None
PCI33, PCIX33, AGP1X33 ³	—	3.3	None
PCIX15	0.75	1.5 ²	None / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
AGP2X33	1.32	—	None
HSTL18_I, II	0.9	1.8 ²	None / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
HSTL18_III, IV	1.08	1.8 ²	None / V _{CCIO} : 50
HSTL15_I, II	0.75	1.5 ²	None / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
HSTL15_III, IV	0.9	1.5 ²	None / V _{CCIO} : 50
SSTL33_I, II	1.5	3.3	None
SSTL25_I, II	1.25	2.5 ²	None / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
SSTL18_I, II	0.9	1.8 ²	None / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
GTL+, GTL	1.0 / 0.8	1.5 / 1.2 ²	None / V _{CCIO} : 50
Differential Interfaces			
SSTL18D_I, II	—	1.8 ²	None / Diff: 120, 150, 220, 420/ Diff to V _{CMT} : 120, 150, 220, 420 / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
SSTL25D_I, II	—	2.5 ²	None / Diff: 120, 150, 220, 420/ Diff to V _{CMT} : 120, 150, 220, 420 / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
SSTL33D_I, II	—	3.3	None
HSTL15D_I, II	—	1.5 ²	None / Diff: 120, 150, 220, 420/ Diff to V _{CMT} : 120, 150, 220, 420 / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
HSTL18D_I, II	—	1.8 ²	None / Diff: 120, 150, 220, 420/ Diff to V _{CMT} : 120, 150, 220, 420 / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
LVDS	—	—	None / Diff: 120, 150, 220, 240/ Diff to V _{CMT} : 120, 150, 220, 240
Mini-LVDS	—	—	None / Diff: 120, 150 / Diff to V _{CMT} : 120, 150
BLVDS25	—	—	None
MLVDS25	—	—	None
RS DS	—	—	None / Diff: 120, 150, 220, 240/ Diff to V _{CMT} : 120, 150, 220, 240
LVPECL33	—	≤2.5	None / Diff: 120, 150, 220, 240/ Diff to V _{CMT} : 120, 150, 220, 240

1. When not specified V_{CCIO} can be set anywhere in the valid operating range.

2. V_{CCIO} needed for on-chip termination to V_{CCIO}/2 or V_{CCIO} only. V_{CCIO} is not specified for off-chip termination or V_{TT} termination.

3. All ratioed input buffers and dedicated pin input buffers include hysteresis with a typical value of 50mV.

Figure 2-27. Output Termination Schemes

Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Series termination (controlled output impedance)		
Parallel termination to V_{CCIO} , or parallel driving end		
Parallel termination to $V_{CCIO}/2$ driving end		
Combined series + parallel termination to $V_{CCIO}/2$ at driving end (only series termination moved on-chip)		
Combined series + parallel to $V_{CCIO}/2$ driving end		

LatticeSC/M Family Timing Adders

Over Recommended Operating Conditions at VCC = 1.2V +/- 5%

Buffer Type	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Input Adjusters								
LVDS	LVDS	-0.031	-0.031	-0.011	-0.011	0.009	0.009	ns
RSDS	RSDS	-0.031	-0.031	-0.011	-0.011	0.009	0.009	ns
BLVDS25	BLVDS	-0.031	-0.031	-0.011	-0.011	0.009	0.009	ns
MLVDS25	MLVDS	-0.031	-0.031	-0.011	-0.011	0.009	0.009	ns
LVPECL33	LVPECL	-0.031	-0.031	-0.011	-0.011	0.009	0.009	ns
HSTL18_I	HSTL_18 class I	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
HSTL18_II	HSTL_18 class II	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
HSTL18_III	HSTL_18 class III	-0.016	-0.018	0.008	0.003	0.032	0.023	ns
HSTL18_IV	HSTL_18 class IV	-0.016	-0.018	0.008	0.003	0.032	0.023	ns
HSTL18D_I	Differential HSTL 18 class I	0.006	0.001	0.029	0.024	0.052	0.046	ns
HSTL18D_II	Differential HSTL 18 class II	0.006	0.001	0.029	0.024	0.052	0.046	ns
HSTL15_I	HSTL_15 class I	-0.005	-0.016	0.026	-0.001	0.057	0.014	ns
HSTL15_II	HSTL_15 class II	-0.005	-0.016	0.026	-0.001	0.057	0.014	ns
HSTL15_III	HSTL_15 class III	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
HSTL15_IV	HSTL_15 class IV	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
HSTL15D_I	Differential HSTL 15 class I	-0.021	-0.022	0.001	-0.009	0.022	0.003	ns
HSTL15D_II	Differential HSTL 15 class II	-0.021	-0.022	0.001	-0.009	0.022	0.003	ns
SSTL33_I	SSTL_3 class I	-0.036	-0.061	-0.181	-0.313	-0.326	-0.565	ns
SSTL33_II	SSTL_3 class II	-0.036	-0.061	-0.181	-0.313	-0.326	-0.565	ns
SSTL33D_I	Differential SSTL_3 class I	0.012	0.012	0.034	0.028	0.055	0.043	ns
SSTL33D_II	Differential SSTL_3 class II	0.012	0.012	0.034	0.028	0.055	0.043	ns
SSTL25_I	SSTL_2 class I	0.003	-0.008	0.03	0.011	0.058	0.03	ns
SSTL25_II	SSTL_2 class II	0.003	-0.008	0.03	0.011	0.058	0.03	ns
SSTL25D_I	Differential SSTL_2 class I	0.006	0	0.031	0.023	0.056	0.046	ns
SSTL25D_II	Differential SSTL_2 class II	0.006	0	0.031	0.023	0.056	0.046	ns
SSTL18_I	SSTL_18 class I	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
SSTL18_II	SSTL_18 class II	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
SSTL18D_I	Differential SSTL_18 class I	0.006	0.001	0.029	0.024	0.052	0.046	ns
SSTL18D_II	Differential SSTL_18 class II	0.006	0.001	0.029	0.024	0.052	0.046	ns
LVTTTL33	LVTTTL	0.034	0.034	-0.05	-0.05	-0.134	-0.134	ns
LVC MOS33	LVC MOS 3.3	0.034	0.034	-0.05	-0.05	-0.134	-0.134	ns
LVC MOS25	LVC MOS 2.5	0	0	0	0	0	0	ns
LVC MOS18	LVC MOS 1.8	-0.068	-0.068	-0.087	-0.087	-0.105	-0.105	ns
LVC MOS15	LVC MOS 1.5	-0.131	-0.131	-0.186	-0.186	-0.241	-0.241	ns
LVC MOS12	LVC MOS 1.2	-0.238	-0.238	-0.364	-0.364	-0.49	-0.49	ns
PCI33	PCI	0.034	0.034	-0.05	-0.05	-0.134	-0.134	ns
PCIX33	PCI-X 3.3	0.034	0.034	-0.05	-0.05	-0.134	-0.134	ns
PCIX15	PCI-X 1.5	-0.005	-0.016	0.026	-0.001	0.057	0.014	ns
AGP1X33	AGP-1X 3.3	0.034	0.034	-0.05	-0.05	-0.134	-0.134	ns
AGP2X33	AGP-2X	-0.036	-0.061	-0.181	-0.313	-0.326	-0.565	ns

sysCLOCK PLL Timing

Over Recommended Operating Conditions

Parameter	Description	Conditions	Min.	Typ	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)		2	—	1000	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)		1.5625	—	1000	MHz
f_{VCO}	PLL VCO Frequency		100	—	1000	MHz
f_{PFD}	Phase Detector Input Frequency		2	—	700	MHz
AC Characteristics						
t_{DT}	Output Clock Duty Cycle	Default duty cycle selected (at 50% levels)	45	—	55	%
t_{OPJIT}^1	Output Clock Period Jitter	$2 \text{ MHz} \leq f_{PFD} \leq 10 \text{ MHz}$	—	—	200	ps
		$f_{PFD} > 10 \text{ MHz}$	—	—	100	ps
t_{CPJIT}^1	Output Clock Cycle-to-Cycle Jitter		—	—	100	ps
t_{SKEW}	Output Clock-to-Clock Skew (Between Two Outputs with the Same Phase Setting)		—	—	20	ps
t_{LOCK}	PLL Lock-in Time		—	—	1	ms
t_{IPJIT}	Input Clock Period Jitter		—	—	± 250	ps
t_{HI}	Input Clock High Time	At 80% level	350	—	—	ps
t_{LO}	Input Clock Low Time	At 20% level	350	—	—	ps
t_{RSWA}	Analog Reset Signal Pulse Width		100	—	—	ns
t_{RSWD}	Digital Reset Signal Pulse Width		3	—	—	ns
t_{DEL}	Timeshift Delay Step Size		40	80	120	ps
t_{RANGE}	Timeshift Delay Range		—	± 560	—	ps
f_{SS}	Spread Spectrum Modulation Frequency		30	—	500	KHz
% Spread	Percentage Downspread for SS Mode		0.5	—	1.5	%
	VCO Clock Phase Adjustment Accuracy		-5	—	5	°

1. Values are measured with FPGA logic active, no additional I/Os toggling and REFCLK total jitter = 30 ps

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AJ1	PB69A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B	PB85A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B
AK1	PB69B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B	PB85B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B
AJ2	PB69C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C	PB85C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C
AH3	PB69D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C	PB85D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C
AH1	PROBE_VCC	-		PROBE_VCC	-	
AH2	PROBE_GND	-		PROBE_GND	-	
AD9	PR57D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A	PR71D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A
AC10	PR57C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A	PR71C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A
AG2	PR57B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E	PR71B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E
AG1	PR57A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E	PR71A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E
AD8	PR56D	3		PR70D	3	
AC9	PR56C	3		PR70C	3	
AF2	PR56B	3		PR70B	3	
AF1	PR56A	3		PR70A	3	
AE6	PR55D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F	PR69D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F
AE7	PR55C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F	PR69C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F
AE1	PR55B	3		PR69B	3	
AE2	PR55A	3		PR69A	3	
AB8	PR53D	3		PR67D	3	
AC8	PR53C	3		PR67C	3	
AE4	PR53B	3		PR67B	3	
AE3	PR53A	3		PR67A	3	
AA10	PR52D	3		PR66D	3	
AA9	PR52C	3		PR66C	3	
AD1	PR52B	3		PR66B	3	
AC1	PR52A	3		PR66A	3	
AC7	PR51D	3	VREF2_3	PR65D	3	VREF2_3
AB7	PR51C	3		PR65C	3	
AD5	PR51B	3		PR65B	3	
AC5	PR51A	3		PR65A	3	
AE5	PR49D	3		PR62D	3	
AF5	PR49C	3		PR62C	3	
AD3	PR49B	3		PR62B	3	
AD4	PR49A	3		PR62A	3	
Y10	PR48D	3		PR61D	3	
Y9	PR48C	3		PR61C	3	
AC2	PR48B	3		PR61B	3	
AD2	PR48A	3		PR61A	3	
AC6	PR47D	3		PR60D	3	
AB6	PR47C	3		PR60C	3	
AA1	PR47B	3		PR60B	3	
AB1	PR47A	3		PR60A	3	
AA5	PR44D	3		PR53D	3	
AB5	PR44C	3		PR53C	3	
Y1	PR44B	3		PR53B	3	
W1	PR44A	3		PR53A	3	
W8	PR43D	3		PR52D	3	
Y7	PR43C	3		PR52C	3	
Y5	PR43B	3		PR52B	3	
W5	PR43A	3		PR52A	3	

LFSC/M115 Logic Signal Connections: 1152 fcBGA^{1, 2}

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AP27	PB26A	5	
AP26	PB26B	5	
AK25	PB26C	5	
AK24	PB26D	5	
AN25	PB29A	5	
AN24	PB29B	5	
AE22	PB29C	5	
AE21	PB29D	5	
AM26	PB31A	5	
AM25	PB31B	5	
AF22	PB31C	5	
AF21	PB31D	5	
AN23	PB47A	5	
AN22	PB47B	5	
AP23	PB57A	5	
AP22	PB57B	5	
AG21	PB57C	5	
AG20	PB57D	5	
AP25	PB50A	5	PCLKT5_3
AP24	PB50B	5	PCLKC5_3
AD21	PB50C	5	PCLKT5_4
AD20	PB50D	5	PCLKC5_4
AL23	PB51A	5	PCLKT5_5
AL22	PB51B	5	PCLKC5_5
AH24	PB51C	5	
AH23	PB51D	5	
AM23	PB53A	5	PCLKT5_0
AM22	PB53B	5	PCLKC5_0
AJ24	PB53C	5	
AJ23	PB53D	5	VREF2_5
AN21	PB54A	5	PCLKT5_1
AN20	PB54B	5	PCLKC5_1
AE19	PB54C	5	PCLKT5_6
AD19	PB54D	5	PCLKC5_6
AK21	PB55A	5	PCLKT5_2
AK20	PB55B	5	PCLKC5_2
AK23	PB55C	5	PCLKT5_7
AK22	PB55D	5	PCLKC5_7
AL20	PB58A	5	
AL19	PB58B	5	
AG19	PB58C	5	
AF19	PB58D	5	
AP21	PB61A	5	

LFSC/M115 Logic Signal Connections: 1152 fcBGA^{1, 2}

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
L5	PR38B	2	
K5	PR38A	2	
G2	PR34B	2	
F2	PR34A	2	
F1	PR30B	2	
E1	PR30A	2	
A2	GND	-	
A33	GND	-	
AA15	GND	-	
AA20	GND	-	
AA32	GND	-	
AA4	GND	-	
AB28	GND	-	
AB6	GND	-	
AC11	GND	-	
AC18	GND	-	
AC25	GND	-	
AD23	GND	-	
AD3	GND	-	
AD31	GND	-	
AE12	GND	-	
AE15	GND	-	
AE29	GND	-	
AE7	GND	-	
AE9	GND	-	
AF20	GND	-	
AF26	GND	-	
AG32	GND	-	
AG4	GND	-	
AH13	GND	-	
AH19	GND	-	
AH25	GND	-	
AH7	GND	-	
AJ10	GND	-	
AJ16	GND	-	
AJ22	GND	-	
AJ28	GND	-	
AK3	GND	-	
AK31	GND	-	
AL11	GND	-	
AL17	GND	-	
AL21	GND	-	
AL27	GND	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB6	PR57D	3		PR71D	3	
AA6	PR57C	3		PR71C	3	
Y2	PR57B	3		PR71B	3	
W2	PR57A	3		PR71A	3	
AB7	PR56D	3		PR70D	3	
AA7	PR56C	3		PR70C	3	
Y3	PR56B	3		PR70B	3	
W3	PR56A	3		PR70A	3	
AC11	PR55D	3		PR69D	3	
AB11	PR55C	3	VREF1_3	PR69C	3	VREF1_3
Y4	PR55B	3		PR69B	3	
W4	PR55A	3		PR69A	3	
AB8	PR52D	3	PCLKC3_2	PR66D	3	PCLKC3_2
AA8	PR52C	3	PCLKT3_2	PR66C	3	PCLKT3_2
Y5	PR52B	3		PR66B	3	
W5	PR52A	3		PR66A	3	
AC12	PR51D	3	PCLKC3_3	PR65D	3	PCLKC3_3
AB12	PR51C	3	PCLKT3_3	PR65C	3	PCLKT3_3
V1	PR51B	3		PR65B	3	
U1	PR51A	3		PR65A	3	
W7	PR50D	3	PCLKC3_1	PR64D	3	PCLKC3_1
V7	PR50C	3	PCLKT3_1	PR64C	3	PCLKT3_1
V2	PR50B	3	PCLKC3_0	PR64B	3	PCLKC3_0
U2	PR50A	3	PCLKT3_0	PR64A	3	PCLKT3_0
AB9	PR48D	2	PCLKC2_2	PR62D	2	PCLKC2_2
AA9	PR48C	2	PCLKT2_2	PR62C	2	PCLKT2_2
T1	PR48B	2	PCLKC2_0	PR62B	2	PCLKC2_0
R1	PR48A	2	PCLKT2_0	PR62A	2	PCLKT2_0
AB10	PR47D	2	PCLKC2_3	PR61D	2	PCLKC2_3
AA10	PR47C	2	PCLKT2_3	PR61C	2	PCLKT2_3
U3	PR47B	2	PCLKC2_1	PR61B	2	PCLKC2_1
T3	PR47A	2	PCLKT2_1	PR61A	2	PCLKT2_1
Y9	PR46D	2		PR60D	2	
W9	PR46C	2		PR60C	2	
V5	PR46B	2		PR60B	2	
U5	PR46A	2		PR60A	2	
AA11	PR43D	2		PR57D	2	
Y11	PR43C	2		PR57C	2	
Y6	PR43B	2		PR57B	2	
W6	PR43A	2		PR57A	2	
Y10	PR42D	2		PR56D	2	
W10	PR42C	2		PR56C	2	
T2	PR42B	2		PR56B	2	
R2	PR42A	2		PR56A	2	
W8	PR41D	2		PR55D	2	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
K14	VCC12	-		VCC12	-	
H11	B_VDDIB2_R	-		B_VDDIB2_R	-	
D8	B_HDINP2_R	-	PCS 3E1 CH 2 IN P	B_HDINP2_R	-	PCS 3E1 CH 2 IN P
E8	B_HDINN2_R	-	PCS 3E1 CH 2 IN N	B_HDINN2_R	-	PCS 3E1 CH 2 IN N
G5	VCC12	-		VCC12	-	
B9	B_HDOUTP2_R	-	PCS 3E1 CH 2 OUT P	B_HDOUTP2_R	-	PCS 3E1 CH 2 OUT P
L12	B_VDDOB2_R	-		B_VDDOB2_R	-	
A9	B_HDOUTN2_R	-	PCS 3E1 CH 2 OUT N	B_HDOUTN2_R	-	PCS 3E1 CH 2 OUT N
C5	B_VDDOB3_R	-		B_VDDOB3_R	-	
A10	B_HDOUTN3_R	-	PCS 3E1 CH 3 OUT N	B_HDOUTN3_R	-	PCS 3E1 CH 3 OUT N
H5	VCC12	-		VCC12	-	
B10	B_HDOUTP3_R	-	PCS 3E1 CH 3 OUT P	B_HDOUTP3_R	-	PCS 3E1 CH 3 OUT P
E9	B_HDINN3_R	-	PCS 3E1 CH 3 IN N	B_HDINN3_R	-	PCS 3E1 CH 3 IN N
D9	B_HDINP3_R	-	PCS 3E1 CH 3 IN P	B_HDINP3_R	-	PCS 3E1 CH 3 IN P
J13	VCC12	-		VCC12	-	
H12	B_VDDIB3_R	-		B_VDDIB3_R	-	
J12	VCC12	-		VCC12	-	
M14	B_REFCLKN_R	-		B_REFCLKN_R	-	
L14	B_REFCLKP_R	-		B_REFCLKP_R	-	
J14	VCC12	-		VCC12	-	
G12	C_VDDIB0_R	-		C_VDDIB0_R	-	
D10	C_HDINP0_R	-	PCS 3E2 CH 0 IN P	C_HDINP0_R	-	PCS 3E2 CH 0 IN P
E10	C_HDINN0_R	-	PCS 3E2 CH 0 IN N	C_HDINN0_R	-	PCS 3E2 CH 0 IN N
H6	VCC12	-		VCC12	-	
B11	C_HDOUTP0_R	-	PCS 3E2 CH 0 OUT P	C_HDOUTP0_R	-	PCS 3E2 CH 0 OUT P
M12	C_VDDOB0_R	-		C_VDDOB0_R	-	
A11	C_HDOUTN0_R	-	PCS 3E2 CH 0 OUT N	C_HDOUTN0_R	-	PCS 3E2 CH 0 OUT N
L11	C_VDDOB1_R	-		C_VDDOB1_R	-	
A12	C_HDOUTN1_R	-	PCS 3E2 CH 1 OUT N	C_HDOUTN1_R	-	PCS 3E2 CH 1 OUT N
K11	VCC12	-		VCC12	-	
B12	C_HDOUTP1_R	-	PCS 3E2 CH 1 OUT P	C_HDOUTP1_R	-	PCS 3E2 CH 1 OUT P
E11	C_HDINN1_R	-	PCS 3E2 CH 1 IN N	C_HDINN1_R	-	PCS 3E2 CH 1 IN N
D11	C_HDINP1_R	-	PCS 3E2 CH 1 IN P	C_HDINP1_R	-	PCS 3E2 CH 1 IN P
H13	VCC12	-		VCC12	-	
C6	C_VDDIB1_R	-		C_VDDIB1_R	-	
H15	VCC12	-		VCC12	-	
G13	C_VDDIB2_R	-		C_VDDIB2_R	-	
D12	C_HDINP2_R	-	PCS 3E2 CH 2 IN P	C_HDINP2_R	-	PCS 3E2 CH 2 IN P
E12	C_HDINN2_R	-	PCS 3E2 CH 2 IN N	C_HDINN2_R	-	PCS 3E2 CH 2 IN N
J9	VCC12	-		VCC12	-	
B13	C_HDOUTP2_R	-	PCS 3E2 CH 2 OUT P	C_HDOUTP2_R	-	PCS 3E2 CH 2 OUT P
K10	C_VDDOB2_R	-		C_VDDOB2_R	-	
A13	C_HDOUTN2_R	-	PCS 3E2 CH 2 OUT N	C_HDOUTN2_R	-	PCS 3E2 CH 2 OUT N
J10	C_VDDOB3_R	-		C_VDDOB3_R	-	
A14	C_HDOUTN3_R	-	PCS 3E2 CH 3 OUT N	C_HDOUTN3_R	-	PCS 3E2 CH 3 OUT N

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AM27	GND	-		GND	-	
AM36	GND	-		GND	-	
AM7	GND	-		GND	-	
AP4	GND	-		GND	-	
AP40	GND	-		GND	-	
AR14	GND	-		GND	-	
AR20	GND	-		GND	-	
AR23	GND	-		GND	-	
AR29	GND	-		GND	-	
AR35	GND	-		GND	-	
AR8	GND	-		GND	-	
AT11	GND	-		GND	-	
AT17	GND	-		GND	-	
AT26	GND	-		GND	-	
AT32	GND	-		GND	-	
AU3	GND	-		GND	-	
AU39	GND	-		GND	-	
AW12	GND	-		GND	-	
AW18	GND	-		GND	-	
AW22	GND	-		GND	-	
AW28	GND	-		GND	-	
AW34	GND	-		GND	-	
AW6	GND	-		GND	-	
AY15	GND	-		GND	-	
AY21	GND	-		GND	-	
AY25	GND	-		GND	-	
AY31	GND	-		GND	-	
AY37	GND	-		GND	-	
AY9	GND	-		GND	-	
B1	GND	-		GND	-	
B42	GND	-		GND	-	
BA1	GND	-		GND	-	
BA42	GND	-		GND	-	
BB2	GND	-		GND	-	
BB41	GND	-		GND	-	
C10	GND	-		GND	-	
C12	GND	-		GND	-	
C13	GND	-		GND	-	
C16	GND	-		GND	-	
C18	GND	-		GND	-	
C19	GND	-		GND	-	
C22	GND	-		GND	-	
C24	GND	-		GND	-	
C27	GND	-		GND	-	
C28	GND	-		GND	-	

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA115EP1-6FC1152C ¹	-6	Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FC1152C ¹	-5	Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FF1152C	-6	Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FF1152C	-5	Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FC1704C ¹	-6	Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FC1704C ¹	-5	Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-6FF1704C	-6	Organic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FF1704C	-5	Organic fcBGA	1704	COM	115.2

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Industrial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA40EP1-6FF1020I ¹	-6	Organic fcBGA	1020	IND	40.4
LFSCM3GA40EP1-5FF1020I ¹	-5	Organic fcBGA	1020	IND	40.4
LFSCM3GA40EP1-6FFA1020I	-6	Organic fcBGA Revision 2	1020	IND	40.4
LFSCM3GA40EP1-5FFA1020I	-5	Organic fcBGA Revision 2	1020	IND	40.4
LFSCM3GA40EP1-6FC1152I ²	-6	Ceramic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-5FC1152I ²	-5	Ceramic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-6FF1152I	-6	Organic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-5FF1152I	-5	Organic fcBGA	1152	IND	40.4

1. Converted to organic flip-chip BGA package revision 2 per [PCN #02A-10](#).2. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA80E-6FC1152I ¹	-6	Ceramic fcBGA	1152	IND	80.1
LFSC3GA80E-5FC1152I ¹	-5	Ceramic fcBGA	1152	IND	80.1
LFSC3GA80E-6FF1152I	-6	Organic fcBGA	1152	IND	80.1
LFSC3GA80E-5FF1152I	-5	Organic fcBGA	1152	IND	80.1
LFSC3GA80E-6FC1704I ¹	-6	Ceramic fcBGA	1704	IND	80.1
LFSC3GA80E-5FC1704I ¹	-5	Ceramic fcBGA	1704	IND	80.1
LFSC3GA80E-6FF1704I	-6	Organic fcBGA	1704	IND	80.1
LFSC3GA80E-5FF1704I	-5	Organic fcBGA	1704	IND	80.1

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA80EP1-6FC1152I ¹	-6	Ceramic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-5FC1152I ¹	-5	Ceramic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-6FF1152I	-6	Organic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-5FF1152I	-5	Organic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-6FC1704I ¹	-6	Ceramic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-5FC1704I ¹	-5	Ceramic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-6FF1704I	-6	Organic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-5FF1704I	-5	Organic fcBGA	1704	IND	80.1

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA80E-7FCN1152C ¹	-7	Lead-Free Ceramic fcBGA	1152	COM	80.1
LFSC3GA80E-6FCN1152C ¹	-6	Lead-Free Ceramic fcBGA	1152	COM	80.1
LFSC3GA80E-5FCN1152C ¹	-5	Lead-Free Ceramic fcBGA	1152	COM	80.1
LFSC3GA80E-7FFN1152C	-7	Lead-Free Organic fcBGA	1152	COM	80.1
LFSC3GA80E-6FFN1152C	-6	Lead-Free Organic fcBGA	1152	COM	80.1
LFSC3GA80E-5FFN1152C	-5	Lead-Free Organic fcBGA	1152	COM	80.1
LFSC3GA80E-7FCN1704C ¹	-7	Lead-Free Ceramic fcBGA	1704	COM	80.1
LFSC3GA80E-6FCN1704C ¹	-6	Lead-Free Ceramic fcBGA	1704	COM	80.1
LFSC3GA80E-5FCN1704C ¹	-5	Lead-Free Ceramic fcBGA	1704	COM	80.1
LFSC3GA80E-7FFN1704C	-7	Lead-Free Organic fcBGA	1704	COM	80.1
LFSC3GA80E-6FFN1704C	-6	Lead-Free Organic fcBGA	1704	COM	80.1
LFSC3GA80E-5FFN1704C	-5	Lead-Free Organic fcBGA	1704	COM	80.1

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA80EP1-7FCN1152C ¹	-7	Lead-Free Ceramic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-6FCN1152C ¹	-6	Lead-Free Ceramic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-5FCN1152C ¹	-5	Lead-Free Ceramic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-7FFN1152C	-7	Lead-Free Organic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-6FFN1152C	-6	Lead-Free Organic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-5FFN1152C	-5	Lead-Free Organic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-7FCN1704C ¹	-7	Lead-Free Ceramic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-6FCN1704C ¹	-6	Lead-Free Ceramic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-5FCN1704C ¹	-5	Lead-Free Ceramic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-7FFN1704C	-7	Lead-Free Organic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-6FFN1704C	-6	Lead-Free Organic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-5FFN1704C	-5	Lead-Free Organic fcBGA	1704	COM	80.1

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA115E-6FCN1152C ¹	-6	Lead-Free Ceramic fcBGA	1152	COM	115.2
LFSC3GA115E-5FCN1152C ¹	-5	Lead-Free Ceramic fcBGA	1152	COM	115.2
LFSC3GA115E-6FFN1152C	-6	Lead-Free Organic fcBGA	1152	COM	115.2
LFSC3GA115E-5FFN1152C	-5	Lead-Free Organic fcBGA	1152	COM	115.2
LFSC3GA115E-6FCN1704C ¹	-6	Lead-Free Ceramic fcBGA	1704	COM	115.2
LFSC3GA115E-5FCN1704C ¹	-5	Lead-Free Ceramic fcBGA	1704	COM	115.2
LFSC3GA115E-6FFN1704C	-6	Lead-Free Organic fcBGA	1704	COM	115.2
LFSC3GA115E-5FFN1704C	-5	Lead-Free Organic fcBGA	1704	COM	115.2

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

For Further Information

For further information about the flexiPCS, see the [LatticeSC/M Family flexiPCS Data Sheet](#).

A variety of technical notes for the LatticeSC/M family are also available on the Lattice Semiconductor website at www.latticesemi.com.

- [LatticeSC PURESPEED I/O Usage Guide](#) (TN1088)
- [LatticeSC PURESPEED I/O Adaptive Input Logic User's Guide](#) (TN1158)
- [LatticeSC sysCLOCK PLL/DLL User's Guide](#) (TN1098)
- [On-Chip Memory Usage Guide for LatticeSC Devices](#) (TN1094)
- [LatticeSC/M DDR/DDR2 SDRAM Memory Interface User's Guide](#) (TN1099)
- [LatticeSC QDRII/II+ SRAM Memory Interface User's Guide](#) (TN1096)
- [LatticeSC sysCONFIG Usage Guide](#) (TN1080)
- [LatticeSC MPI/System Bus](#) (TN1085)
- [SPI Serial Flash Programming Using ispJTAG in LatticeSC Devices](#) (TN1100)
- [Power Estimation and Management for LatticeSC Devices](#) (TN1101)
- [LatticeSC SERDES Jitter](#) (TN1084)
- [LatticeSC FPGAs: Implementing 3.3V Interfaces in 2.5V VCCIO Banks](#) (TN1110)
- [Lattice PCI Express Basic Demo User's Guide](#) (UG08)
- [LatticeSC flexiPCS/SERDES Design Guide](#) (TN1145)
- [Temperature Sensing Diode in LatticeSC Devices](#) (TN1115)
- [SPI4.2 Interoperability Between ORSPI4 and LatticeSC Devices](#) (TN1116)

For further information on Interface standards refer to the following websites:

- JEDEC Standards (LVTTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- Optical Interface (SPI-4.2, XSBI, CSIX and XGMII): www.oiforum.com
- RAPIDIO: www.rapidio.org
- PCI/PCIX: www.pcisig.com

Date	Version	Section	Change Summary
March 2007 (cont.)	01.5 (cont.)	DC and Switching Characteristics (cont.)	Updated LatticeSC Internal Timing Parameters with ispLEVER 6.1 SP1 results.
			Updated t_{FDEL} and t_{CDEL} specifications.
			Updated LatticeSC Family Timing Adders with ispLEVER 6.1 SP1 results.
			Updated PLL specifications to expand frequency range down to 2 MHz and break out jitter for the different ranges.
			Added footnote to sysCLOCK PLL Timing table specifying the conditions for the jitter measurements.
			Added t_{DLL} specification to sysCLOCK DLL Timing table.
			Added footnote to sysCLOCK DLL Timing table specifying the conditions for the jitter measurements.
			Added sysCONFIG Master Parallel Configuration Mode and sysCONFIG SPI Port to LatticeSC sysCONFIG Port Timing table.
		Pin Information	Updated Pin Information Summary with SC40 information.
			Updated LFSC25 Logic Signal Connections: FF1020 with SC40 information.
			Updated LFSC80 Logic Signal Connections: FC1152 with SC40 information.
August 2007	01.6	General	Changed references of "HDC" to "HDC/SI".
			Changed references of "LDCN" to "LDCN/SCS".
			Changed references of "BUSYN/RCLK" to "BUSYN/RCLK/SCK".
			Changed references of "RDCFGN" to "TSALLN".
			Changed references of "TDO/RDDATA" to "TDO".
		Architecture	Updated text in Ripple Mode section.
			Added information to Global Set/Reset.
			Added information for Spread Spectrum Clocking
			Modified information for PLL/DLL Cascading. DLL to PLL is now supported.
			Modified AIL Block text and figure.
			Modified Figure 2-20 DDR/Shift Register Block.
			Added Information to Hot Socketing.
			Added new information for I/O Architecture Rules.
			Added information to SERDES Power Supply Sequencing Requirements.
		DC and Switching Characteristics	Added footnote to Hot Socketing Specifications table.
			Modified Initialization and Standby Supply Current table.
			Modified GSR Timing table.
			Modified sysCLOCK DLL Timing table to include I_{DUTY} .
			Deleted Readback Timing information from sysCONFIG Port Timing table.
			Modified data in External Switching Characteristics table.
		Pin Information	Added information to the Signal Descriptions table for HDC/SI, LDCN/SCS.
			Added footnote to Signal Descriptions table.
			Modified Description for signal BUSYN/RCLK/SCK.
			Modified data in Pin Information Summary and device-specific Pinout Information tables.

Date	Version	Section	Change Summary
September 2007	01.7	Pinout Information	Added Thermal Management text section.
		Supplemental Information	Updated title list.
November 2007	01.8	Ordering Information	Removed -7 speed grade information for 115K LUT devices in the Ordering Information tables.
January 2008	01.9	Introduction	Corrections/Additions to memory controller list (Tables 1-2).
		Architecture	AIL Overview – Modified power used by AIL block.
			PURESPEED I/O Buffer Banks – Modified VTT termination info. Added info about complimentary drivers for all banks.
			Supported Source Synchronous Interfaces – Modified data for DDRII in Table 2-11.
		DC and Switching Characteristics	Recommended Operating Conditions – Changed footnote 3.
			Initialization and Standby Supply Current – Inserted a paragraph with info regarding the table. Also updated the table.
			Typical Building Block Function Performance – Added VCC=1.2V=1.2V+/-5% above Pin to Pin Performance table.
			LatticeSC External Switching Characteristics – Added VCC=1.2V=1.2V+/-5% above table. Reworded footnote 3.
			LatticeSC Family Timing Adders – Added VCC=1.2V=1.2V+/-5% above table.
			LatticeSC Internal Timing Parameters – Added VCC=1.2V=1.2V+/-5% above table. Reworded footnote 1.
			GSR Timing – Added a new table for Internal System Bus Timing after GSR Timing.
			LatticeSC sysCONFIG Port Timing – Corrected sysCONFIG SPI Port information.
		Pinout Information	Signal Descriptions – Modified info for VTT_x, PROBE_VCC, and PROBE_GND. Modified info for [LOC]_DLL[T,C]_IN[C,D,E,F].
		Supplemental Information	Updated list of technical notes, added reference to LatticeSC/M flexiPCS Data Sheet.
March 2008	02.0	DC and Switching Characteristics	Updated Internal Timing Parameters table.
			Updated Read Mode timing diagram.
			Updated Read Mode with Input Registers Only timing diagram.
June 2008	02.1	—	Data sheet status changed from preliminary to final.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
		DC and Switching Characteristics	Updated LatticeSC/M External Switching Characteristics table.
			Updated LatticeSC/M Internal Timing Parameters table.
December 2008	02.2	Architecture	Removed Read-Before-Write sysMEM EBR mode.
			Output/Tristate DDR/Shift Register Block Diagram - corrected connection to POS.
			DC and Switching Characteristics table - updated data for t_{SUI_PIO} .
		Multiple	Added T_R , T_F parameter to PURESPEED I/O Differential Electrical Characteristics (LVDS) table.
January 2010	02.3	Multiple	Removed references to HyperTransport throughout the data sheet.
		Introduction	Updated per PCN #01A-10 (ceramic fcBGA conversion to organic fcBGA for the 1152-ball and 1704-ball fcBGA packages) and PCN #02A-10 (1020-ball organic fcBGA conversion to 1020-ball organic fcBGA revision 2 package).
		Ordering Information	